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Apalis Heatsink Type 0

HW Errata

Revision History

Document Revisions

Date	Doc. Revision	Product Version	Changes
15-Apr-2026	Rev. 0.1	V1.0	Initial release

Contents

1 Errata #1: HAR-13573 – TIM Hardness on Type 0 V1.0A Can Cause Excessive Pressure and PCB Bending on Apalis iMX8 Modules

Affected version:

Apalis Heatsink Type 0 V1.0A

Fixed in:

Apalis Heatsink Type 0 V1.0B

1.1 Customer Impact

Customers using the Apalis Heatsink Type 0 V1.0A with Apalis iMX8 family modules in their designs may experience PCB bending due to the excessive pressure applied by the TIM. This can lead to potential solder joint fatigue, intermittent electrical connections, or premature field failures, particularly in applications subject to thermal cycling or mechanical stress. Customers currently in production or late-stage design with this heatsink and Apalis iMX8 modules should evaluate the workaround below and plan accordingly to avoid reliability risks in deployed units.

1.2 Description

The Thermal Interface Material (TIM) used on the Apalis Heatsink Type 0 V1.0A has a hardness that is too high. When the heatsink is mounted on Apalis iMX8 family computer modules, the TIM can exert excessive mechanical pressure on the module, which may result in PCB bending. This deformation can potentially affect solder joint reliability and long-term product integrity.

1.3 Workaround

Please use the Apalis Heatsink Type 4 instead.

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